

ELECTRONIC DEVICE TESTING APPARATUSABSTRACT OF THE DISCLOSURE

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An IC chip testing apparatus provided with an IC socket 206 to which an IC chip is brought into electrical contact, a printed circuit board 205 with one terminal which is electrically connected to a terminal of a test head and with another terminal which is electrically connected to a terminal of the IC socket 206, and a heating element 208 provided at the printed circuit board 205. The IC chip testing apparatus may be provided with a socket 320 to which an IC chip to be tested is detachably mounted; a socket guide 382 holding the socket 320; a chamber 306 to the opening 392 of which the socket guide 382 is attached so that an IC chip mounting opening of the socket 320 faces inside the chamber and able to maintain the inside at a predetermined state less than ordinary temperature; a printed circuit board 400 which is electrically connected to a terminal of the socket 320 and which is arranged at the outside of the chamber opening 392 of the chamber 6; and a heating board 406 which is provided around the chamber opening 392 of the chamber 306 and heats the printed circuit board 400 by heat conduction. It is possible to prevent condensation of the printed circuit board which tends to occur at the time of application of a low temperature and radiation of heat from the IC socket which tends to occur at the time of application of a high temperature or low temperature.

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